

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	L14 and (grinding near edge near chip)	4	<u>L15</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	L12 and grind\$3	507	<u>L14</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	L12 and (edge near (die or chip))	233	<u>L13</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(grind\$3 or ground) with edge\$1 with (chip\$1 or die or dies or dice)	838	<u>L12</u>
USPT	(5196378 or 5773368).pn.	2	<u>L11</u>
PGPB,JPAB,EPAB,DWPI,TDBD	L9 and (stepped or vertical or teired or multiple or transverse or perpendicular)	77	<u>L10</u>
PGPB,JPAB,EPAB,DWPI,TDBD	(profile or perimeter or polish\$3 or grind\$3) same ((die or dice) with edge\$1)	438	<u>L9</u>
USPT	l7 not l6	2	<u>L8</u>
USPT	L5 and dicing	6	<u>L7</u>
USPT	L5 and diced	9	<u>L6</u>
USPT	(polish\$3 or grind\$3 or profile) with edge\$1 with (die or dice)	416	<u>L5</u>
USPT	L3 and ((profile or geometry or grind\$3 or smooth\$3 or flat\$6 or polish\$3 or hon\$3 or etch\$3) with edge\$1)	248	<u>L4</u>
USPT	L1 or L2	1440	<u>L3</u>
USPT	((257/618 257/619 257/620)!.CCLS.)	531	<u>L2</u>
USPT	((438/114 438/113 438/460 438/461 438/462 438/463 438/464 438/465)!.CCLS.)	972	<u>L1</u>

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Term:

(grinding with edge with chip)

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USPT	(grinding with edge with chip)	126	<u>L3</u>
USPT	(grinding with edge with chip).ti.	0	<u>L2</u>
USPT	(grinding with edge with die).ti.	0	<u>L1</u>

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Term:

L9 and (stepped or vertical or teired or multiple
 or transverse or perpendicular)

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<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
PGPB,JPAB,EPAB,DWPI,TDBD	L9 and (stepped or vertical or teired or multiple or transverse or perpendicular)	77	<u>L10</u>
PGPB,JPAB,EPAB,DWPI,TDBD	(profile or perimeter or polish\$3 or grind\$3) same ((die or dice) with edge\$1)	438	<u>L9</u>
USPT	17 not 16	2	<u>L8</u>
USPT	L5 and dicing	6	<u>L7</u>
USPT	L5 and diced	9	<u>L6</u>
USPT	(polish\$3 or grind\$3 or profile) with edge\$1 with (die or dice)	416	<u>L5</u>
USPT	L3 and ((profile or geometry or grind\$3 or smooth\$3 or flat\$6 or polish\$3 or hon\$3 or etch\$3) with edge\$1)	248	<u>L4</u>
USPT	L1 or L2	1440	<u>L3</u>
USPT	((257/618 257/619 257/620)!.CCLS.)	531	<u>L2</u>
USPT	((438/114 438/113 438/460 438/461 438/462 438/463 438/464 438/465)!.CCLS.)	972	<u>L1</u>